

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification#20231207005.0A Device symbolization update for Select Devices Information Only

Date: May 28, 2024 **To:** Digi- Key PCN

Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification.

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team SC Business Services

20231207005.A Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV8848PWP	null
TPA3120D2PWP	null
TPS54110PWP	null
TPS54110PWPR	null
TPS54380PWPR	null
TPS54680PWP	null
TPS54810PWP	null
TPS54810PWPR	null
TPS54873PWP	null
TPS54873PWPR	null
TPS54910PWP	null
TPS54910PWPR	null
TPS70302PWPR	null
TPS767D301MPWPREP	null
TPS76801MPWPREP	null

Technical details of this Product Change follow on the next page(s).

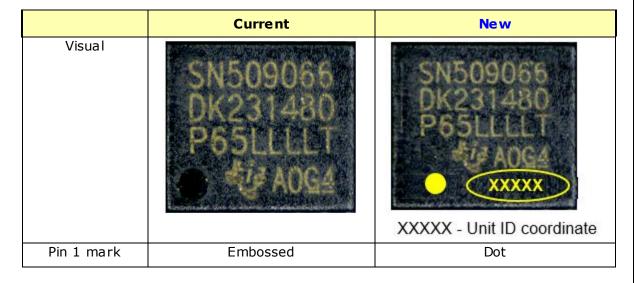
Notification Number: 20231			.207005.0 <mark>A</mark>			Notification Date:			May 28, 2024		
Titl	Title: Device symbolization update for Select Devices										
Customer Contact: Change Man			nage	gement team Dept:			Quality Services				
Change Type:											
	Assembly Site				Design				Wafer Bump Material		
	Assembly Process				Data Sheet				Wafer Bump Process		
	Assembly Materials				Part number change				Wafer Fab Site		
	■ Mechanical Specification				Test Site				Wafer Fab Materials		
\boxtimes	□ Packing/Shipping/Labeling				Test Process				Wafer Fab Process		
Notification Details											

Description of Change:

Revision A is to announce the addition of new devices that were not included on the original PCN notification. These new devices are included on page 2 of this document. For devices in the original publication, please refer to page 2 of that publication.

Texas Instruments Incorporated is announcing an update to device symbolization marking for Select Devices as follows:

Change #1: All devices will start having the mold cavity id included in the device marking for enhanced device level traceability as follows:



Change #2: Devices Symbolization update (for this change below, some of the devices were on previous PCNs for this change):

	Current	New
**ECAT	Include Value	Remove
TI Bug	Include	Replace with "TI" text



** - Not all devices have ECAT information included in the symbolization, but for the ones that do, this information will be removed.

Reason for Change:

Improved internal traceability

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Device marking change only

Changes to product identification resulting from this notification:

Device marking change only. No change to pack labels.

Product Affected:

See page 2

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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